Title (en)

METHOD FOR THE HOT STAMPING OF AT LEAST ONE CONDUCTOR TRACK ONTO A SUBSTRATE, SUBSTRATE COMPRISING AT LEAST ONE CONDUCTOR TRACK AND STAMPING TOOL

Title (de)

VERFAHREN ZUM HEISSPRÄGEN MINDESTENS EINER LEITERBAHN AUF EIN SUBSTRAT, SUBSTRAT MIT MINDESTENS EINER LEITERBAHN SOWIE PRÄGESTEMPEL

Title (fr)

PROCÉDÉ D'ESTAMPAGE À CHAUD D'AU MOINS UNE PISTE CONDUCTRICE SUR UN SUBSTRAT, SUBSTRAT POURVU D'AU MOINS UNE PISTE CONDUCTRICE ET POINÇON D'ESTAMPAGE

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Application

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Abstract (en)

[origin: WO2010012540A1] The invention relates to a method for the hot stamping of at least one conductor track (17) onto a substrate (1), wherein a film (3) having at least one electrically conductive layer (4) is pressed against the substrate (1) in a stamping direction (16) by means of a stamping tool (7) having a structured stamping surface (8). The invention provides for the film (3) to be stamped in such a way that the conductor track (17) acquires three-dimensional shaping. Furthermore, the invention relates to a substrate (1) and also a stamping tool (7).

IPC 8 full level

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CPC (source: EP)

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